

## CLAIMS

What is claimed is:

1. A method for bonding a conductive element to a contact of a semiconductor device component, comprising:  
providing a semiconductor device component with at least one contact; and  
defining at least two layers of at least one conductive element from corresponding layers comprising substantially unconsolidated conductive material.
  
2. The method of claim 1, wherein said defining comprises causing said substantially unconsolidated conductive material in selected regions of said layers to at least partially consolidate.
  
3. The method of claim 1, further comprising, following said defining, permitting said substantially unconsolidated conductive material to at least partially consolidate.
  
4. The method of claim 1, wherein said providing said semiconductor device component comprises providing a carrier substrate.
  
5. The method of claim 1, wherein said providing said semiconductor device component comprises providing a semiconductor die.
  
6. The method of claim 1, wherein said providing said semiconductor device component comprises providing a packaged semiconductor device.
  
7. The method of claim 1, wherein said defining comprises defining said at least two layers from an at least partially liquified thermoplastic conductive elastomer.

8. The method of claim 7, further comprising, following said defining, permitting said at least partially liquified thermoplastic conductive elastomer to at least partially consolidate.

9. The method of claim 8, wherein said permitting said conductive material to at least partially consolidate comprises permitting said conductive material to at least partially harden.

10. The method of claim 1, wherein said defining comprises defining said at least two layers from an at least partially uncured conductive photopolymer.

11. The method of claim 10, wherein said defining comprises causing said at least partially uncured conductive photopolymer to at least partially consolidate.

12. The method of claim 11, wherein said causing said conductive material to at least partially consolidate comprises directing a laser beam onto selected regions of said layers of substantially unconsolidated conductive material.

13. The method of claim 1, wherein said defining comprises defining said at least two layers from metal particles.

14. The method of claim 13, wherein said defining comprises defining said at least two layers from resin-coated metal.

15. The method of claim 13, wherein said defining comprises securing said metal particles in selected regions of said layers of substantially unconsolidated conductive material to adjacent metal particles.

16. The method of claim 15, wherein said securing comprises directing an energy beam onto selected regions of said layers of substantially unconsolidated conductive material.